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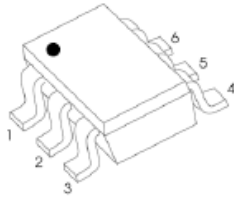
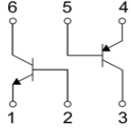
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PLED

Product data sheet

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SOT-363

**BC847PN** DUAL TRANSISTOR (NPN+PNP)

**FEATURES**

- Epitaxial Die Construction
- Two isolated NPN/PNP(BC847W+BC857W) Transistors in one package

**MAKING: 7P**
**MAXIMUM RATINGS TR1 (T<sub>a</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Value	Units
V <sub>CB0</sub>	Collector-Base Voltage	50	V
V <sub>CEO</sub>	Collector-Emitter Voltage	45	V
V <sub>EBO</sub>	Emitter-Base Voltage	6	V
I <sub>c</sub>	Collector Current –Continuous	0.1	A
P <sub>c</sub>	Collector Power Dissipation	200	mW
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55-150	°C

**CHARACTERISTICS of TR1 (NPN Transistor) (T<sub>a</sub>=25°C unless otherwise specified)**

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =10μA, I <sub>E</sub> =0	50			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =0	45			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =1μA, I <sub>C</sub> =0	6			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =30V, I <sub>E</sub> =0			15	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =5V, I <sub>C</sub> =0			15	nA
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =2mA	200		450	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =0.5mA			0.25	V
	V <sub>CE(sat)</sub>	I <sub>C</sub> =100mA, I <sub>B</sub> =5mA			0.6	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =0.5mA		0.7		V
	V <sub>BE(sat)</sub>	I <sub>C</sub> =100mA, I <sub>B</sub> =5mA		0.9		V
Base-emitter voltage	V <sub>BE(on)</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =2mA	0.58		0.7	V
	V <sub>BE(on)</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =10mA			0.72	V
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =10V, I <sub>E</sub> =0, f=1MHz			6.0	pF
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> =5V, I <sub>C</sub> =10mA, f=100MHz	100			MHz
Noise figure	NF	V <sub>CE</sub> =5V, I <sub>C</sub> =0.2mA, f=1kHz, R <sub>g</sub> =2KΩ, Δf=200Hz			10	dB

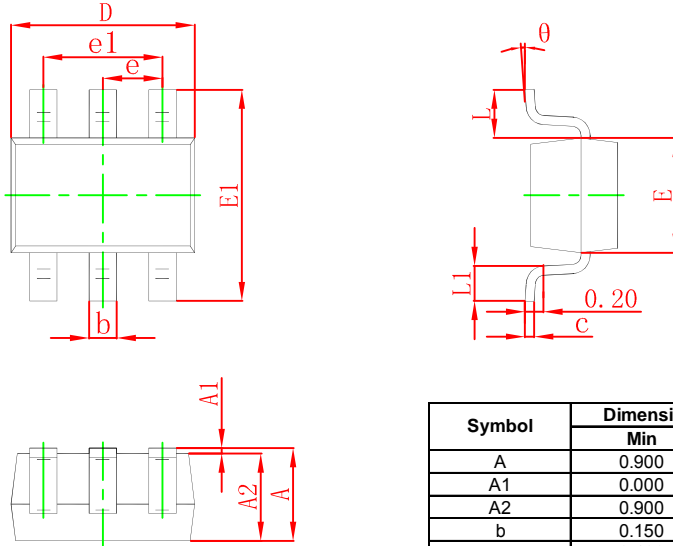
**MAXIMUM RATINGS TR2 (T<sub>a</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Value	Units
V <sub>CB0</sub>	Collector-Base Voltage	-50	V
V <sub>CE0</sub>	Collector-Emitter Voltage	-45	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
I <sub>C</sub>	Collector Current –Continuous	-0.1	A
P <sub>C*</sub>	Collector Power Dissipation	200	mW
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55-150	°C

**CHARACTERISTICS of TR2 (PNP Transistor) (T<sub>a</sub>=25°C unless otherwise specified)**

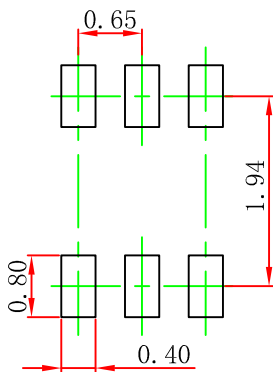
Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-10μA, I <sub>E</sub> =0	-50			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =-10mA, I <sub>B</sub> =0	-45			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =-1μA, I <sub>C</sub> =0	-5			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> =-30V, I <sub>E</sub> =0			-15	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =-5V, I <sub>C</sub> =0			-15	nA
DC current gain	h <sub>FE1</sub>	V <sub>CE</sub> =-5V, I <sub>C</sub> =-2mA	220		475	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =-10mA, I <sub>B</sub> =-0.5mA			-0.3	V
	V <sub>CE(sat)</sub>	I <sub>C</sub> =-100mA, I <sub>B</sub> =-5mA			-0.65	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	I <sub>C</sub> =-10mA, I <sub>B</sub> =-0.5mA		-0.7		V
	V <sub>BE(sat)</sub>	I <sub>C</sub> =-100mA, I <sub>B</sub> =-5mA			-0.95	V
Base-emitter voltage	V <sub>BE(on)</sub>	V <sub>CE</sub> =-5V, I <sub>C</sub> =-2mA	-0.6		-0.75	V
	V <sub>BE(on)</sub>	V <sub>CE</sub> =-5V, I <sub>C</sub> =-10mA			-0.82	V
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =-10V, I <sub>E</sub> =0, f=1MHz			4.5	pF
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> =-5V, I <sub>C</sub> =-10mA, f=100MHz	100			MHz
Noise figure	NF	V <sub>CE</sub> =-5V, I <sub>c</sub> =-0.2mA, f=1kHz, R <sub>g</sub> =2KΩ, Δf=200Hz			10	dB

**SOT-363 Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

**SOT-363 Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance: ± 0.05mm.
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
BC847PN	SOT-363	3000

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